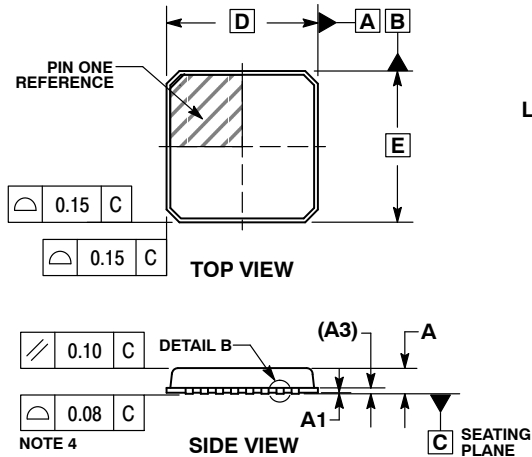


SCALE 2:1

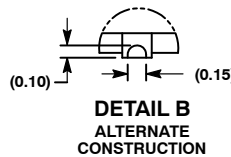
QFN32 5x5, 0.5P (PUNCHED)
CASE 485CZ
ISSUE A

DATE 29 JUL 2013

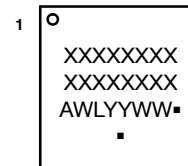


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSIONS: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	0.90
A1	---	0.05
A3	0.20	REF
b	0.20	0.30
D	5.00	BSC
D2	3.20	3.40
E	5.00	BSC
E2	3.20	3.40
e	0.50	BSC
L	0.30	0.50



GENERIC
MARKING DIAGRAM*

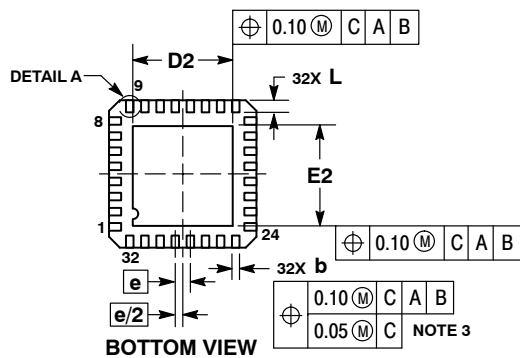


- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

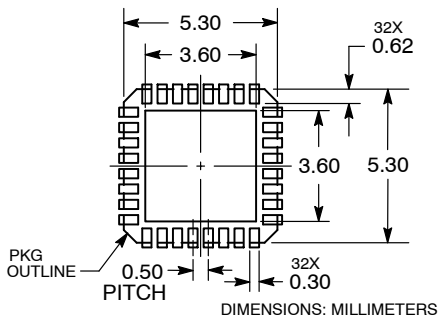
(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot "▪", may or may not be present.



RECOMMENDED
SOLDERING FOOTPRINT



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DESCRIPTION:	QFN32 5x5, 0.5P (PUNCHED)	PAGE 1 OF 1

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